## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit of parent application: 2823 Examiner of parent application: Thanh V Pham

	APPLICATION Of: : kazuaki YOSHIIKE	
Appln. No.	: To Be Assigned	) )
Div of Ser. No	: 10/300,782 filed November 21, 2002, which) is a division of 09/782,163 filed February 14, 2001	
Filed	: Herewith	PRELIMINARY  AMENDMENT
For	: LEAD FRAME FOR RESIN SEALED SEMICONDUCTOR DEVICE (amended)	) )
Attorney Ref.:	F99ED0138-DIV-DIV	)
		July 23, 2003

**BOX: Non-Fee Amendment** 

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

Sir:

Preliminary to examination, please amend the application as follows:

## **TITLE AMENDMENT**

Please amend the title of the invention as follows,

MOLDING APPARATUS FOR USE IN MANUFACTURING OF RESIN SHIELDING SEMICONDUCTOR DEVICE, AND A LEAD FRAME FOR RESIN SEALED SEMICONDUCTOR THE DEVICE, AND A METHOD OF USING THE APPARATUS